



HIGH-DENSITY BACKPLANE HEADERS & SOCKETS

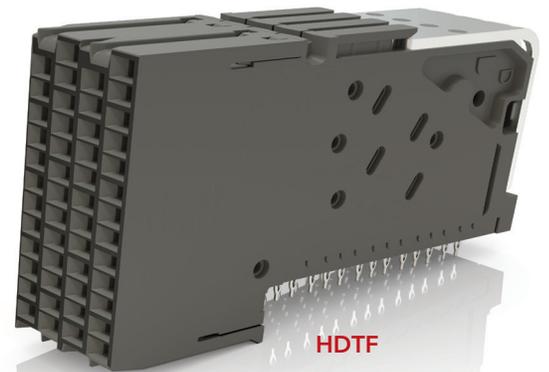
(1.80mm) .071" PITCH

FEATURES & BENEFITS

- Small form factor and modular design provides significant space-savings and flexibility
- High-performance system
- Up to 84 differential pairs per linear inch
- 3, 4 and 6-pair designs on 4, 6 and 8 columns
- Integrated power, guidance, keying and side walls available
- 85 Ω and 100 Ω options
- Combine any configuration of modules to create one integrated receptacle (BSP Series); corresponding terminal modules are individually mounted to the backplane



HDTM



HDTF

XCede® HD

16
Gbps

SMALL FORM FACTOR



3, 4 and 6-pair designs

DENSITY COMPARISON



XCede® HD

Up to 84 pairs per linear inch

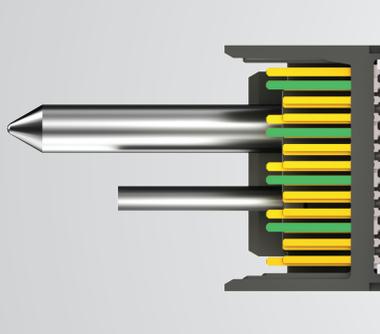


Traditional Backplane

Up to 76 pairs per linear inch

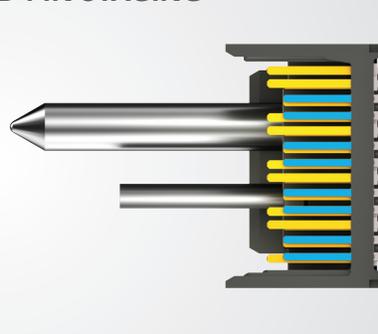
(Both shown with six 4-pair, 8 column receptacles)

SIGNAL/GROUND PIN STAGING



Ground Pins

Ground pins mate before signal pin pairs for hot plugging, preventing system downtime



Signal Pins

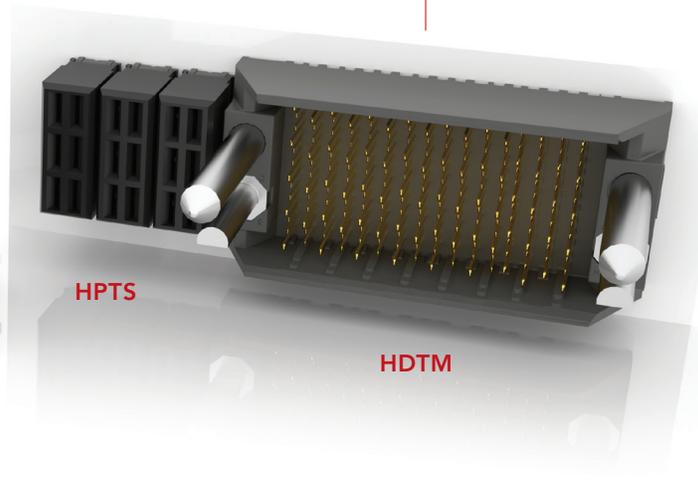
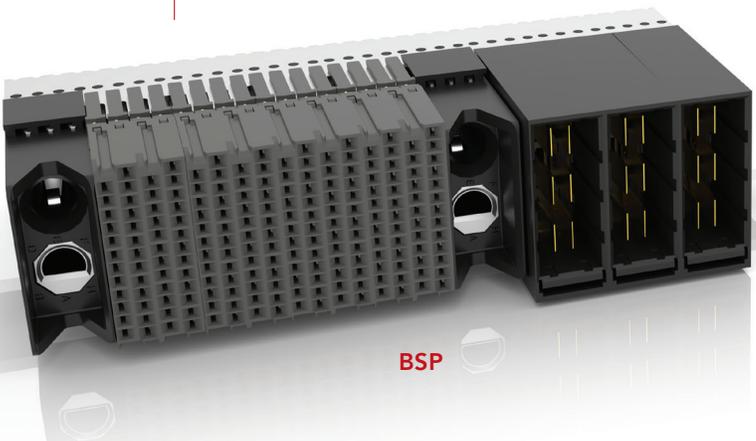
Signal pin pairs achieve up to 3.00 mm contact wipe for a reliable connection

MODULAR DESIGN

XCede® HD consists of signal, power and keying/guidance modules for incredible design flexibility. The modules can be customized in any configuration to meet specific application requirements. Contact HSBP@samtec.com for more information about building a full XCede® HD solution.

How to build a full solution:

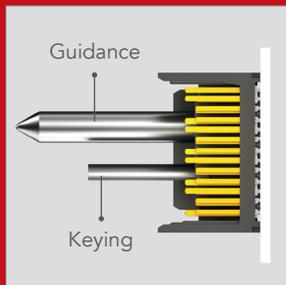
- ① Right-angle modules can be built into a single customizable BSP
- ② Build a BSP part by combining any number, in any configuration, of HDTFs, power and keying/guidance modules to create one receptacle
- ③ Header modules mount to the backplane individually, in any configuration of HDTM and HPTS Series



XCede® is a registered trademark of Amphenol Corporation.

PRODUCT BREAKDOWN

(BSP Custom Configuration Shown)



Side View
(HDTM/HPTS Series)

